

### 1 Scope

The present specifications shall apply to a FMU-G26S.

### 2 Outline

#### High Frequency Rectification

Type	Silicon Diode
Structure	Resin Molded
Applications	High Frequency Rectification

### 3 Flammability

UL94V-0(Equivalent)

*Not Recommended for New Designs*

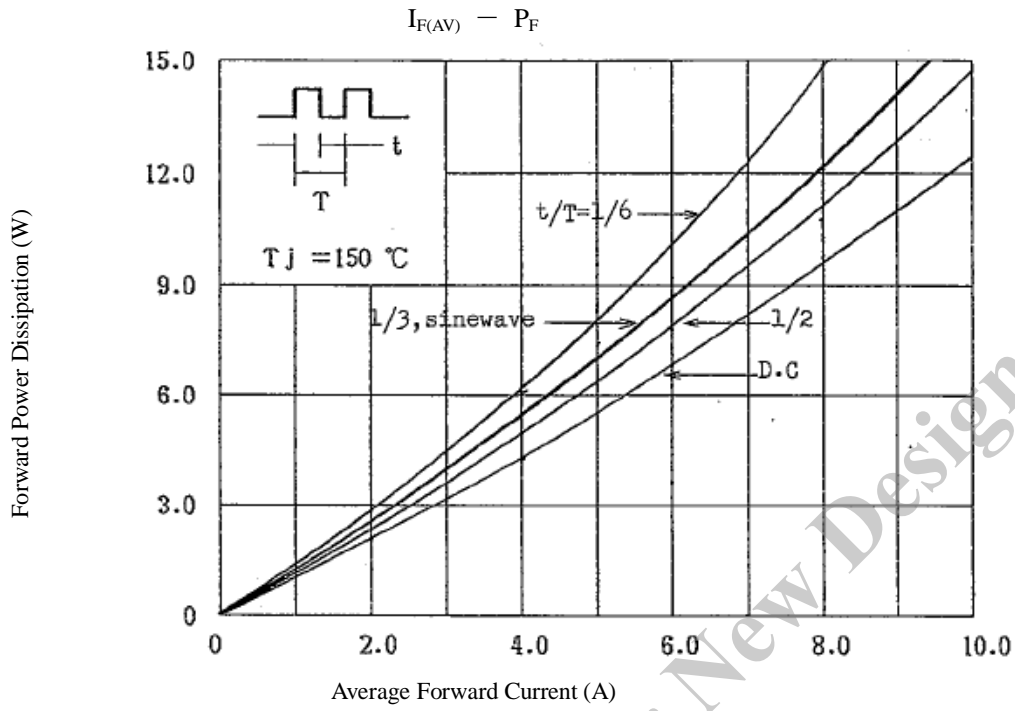
## 4 Absolute maximum ratings

No.	Item	Symbol	Unit	Rating	Conditions
1	Transient Peak Reverse Voltage	$V_{RSM}$	V	600	
2	Peak Reverse Voltage	$V_{RM}$	V	600	
3	Average Forward Current	$I_{F(AV)}$	A	10	Refer to Derating of 7
4	Peak Surge Forward Current	$I_{FSM}$	A	40	10ms. Half sinewave, one shot
5	$I^2t$ Limiting Value	$I^2t$	$A^2s$	8	$1ms \leq t \leq 10ms$
6	Junction Temperature	$T_j$	$^{\circ}C$	-40 to +150	
7	Storage Temperature	$T_{stg}$	$^{\circ}C$	-40 to +150	
8	Dielectric Strength		kV	A.C.1.0	Lead and Case (1min.)

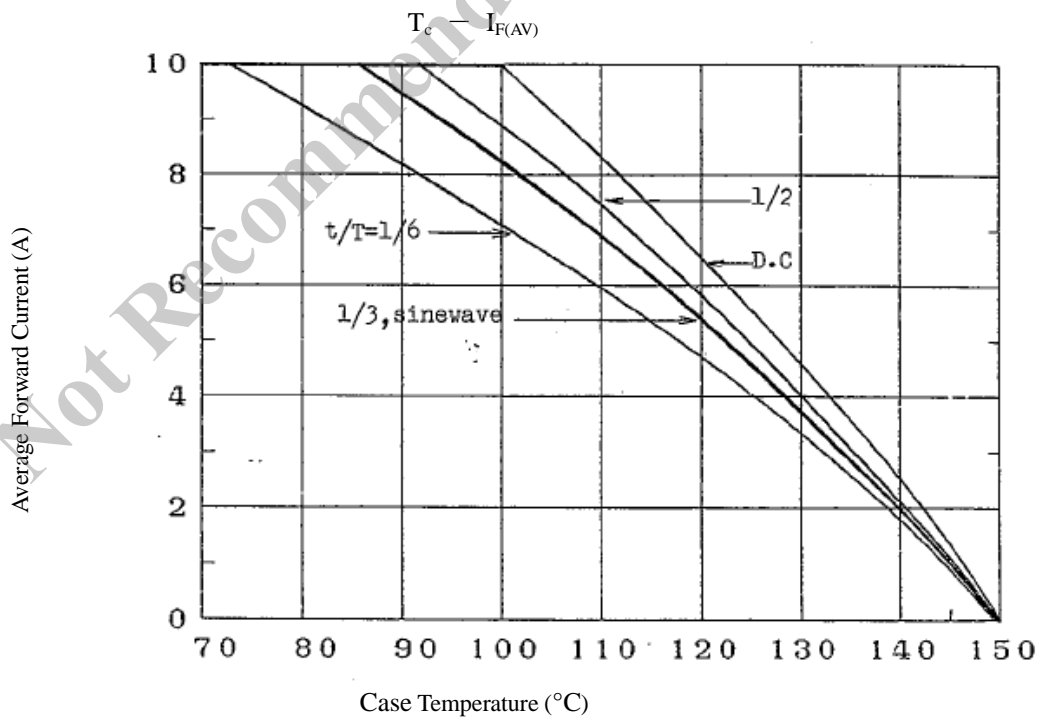
## 5 Electrical characteristics (Ta=25°C, unless otherwise specified)

No.	Item	Symbol	Unit	Value	Conditions
1	Forward Voltage Drop	$V_F$	V	1.35 max.	$I_F=10A$
2	Reverse Leakage Current	$I_R$	$\mu A$	50 max.	$V_R=V_{RM}$
3	Reverse Leakage Current Under High Temperature	$H \cdot I_R$	$\mu A$	500 max.	$V_R=V_{RM}, T_j=150^{\circ}C$
4	Reverse Recovery Time	trr1	ns	400 max.	$I_F=I_R=100mA$ , 90% Recovery point
		trr2	ns	200 max.	$I_F=100mA, I_R=200mA$ , 75% Recovery point
5	Thermal Resistance	$R_{th(j-c)}$	$^{\circ}C/W$	4.0 max.	Between Junction and case

6 Characteristics

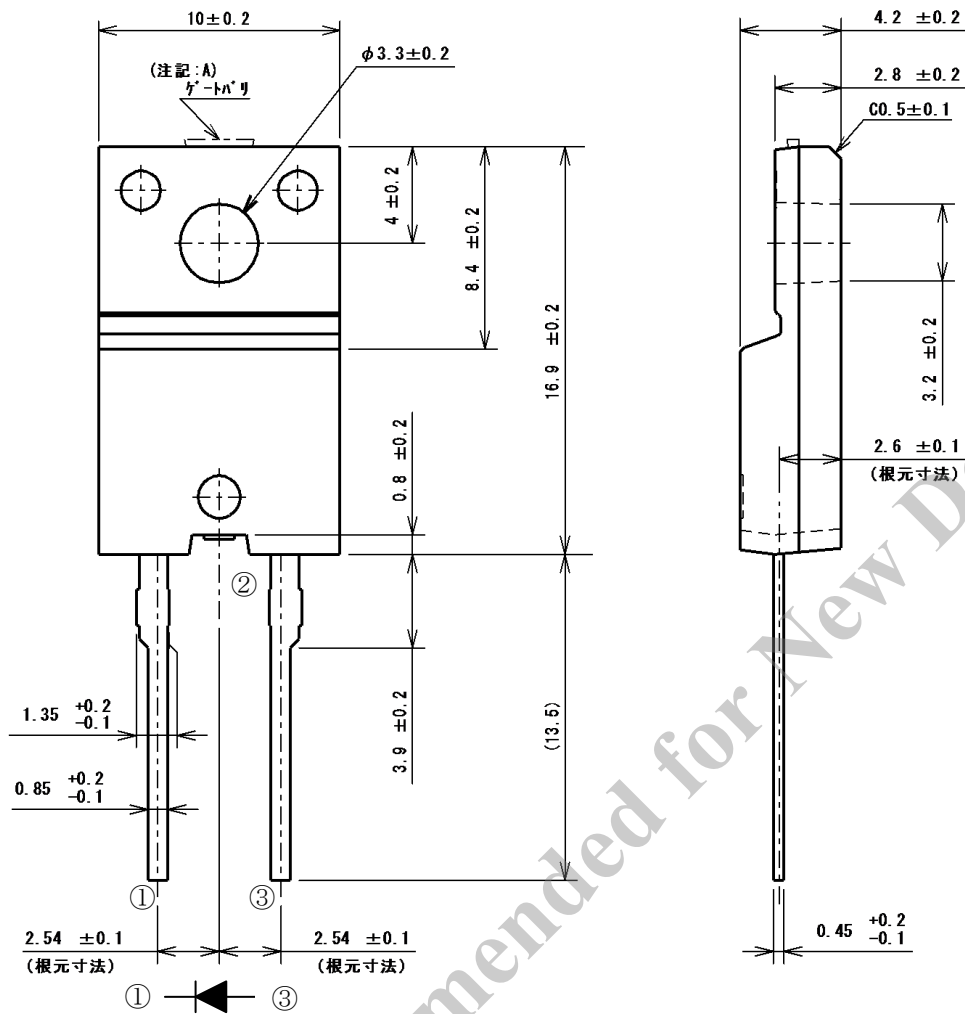


7 Derating



8 Package information

8-1 Package type, physical dimensions and material



注記:A ・ 図中ゲートバリ部は高さ0.3maxのゲートバリ発生箇所を示します。

Dimensions in mm

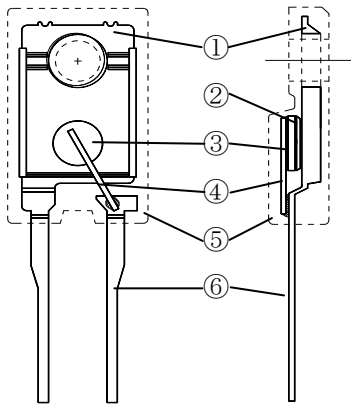
8-2 Appearance

The body shall be clean and shall not bear any stain, rust or flaw.

8-3 Marking

Type Name	Marking		
	*1 Type Name	*2 Polarity	*3 Lot number
FMU-G26S	FMUG26	S	1st letter: Last digit of year 2nd letter: Month From 1 to 9 for Jan. to Sep., O for Oct., N for Nov., D for Dec. 3rd & 4th letter: Day ex. 8723 (July 23, 2008)

9 Internal structure diagram



Weight of products: Approx. 2.1g

No.	Name of part	Materials
①	Frame: Heat Sink	Nickel Plated Copper
②	Chip	Silicon
③	Disc	Nickel plated copper
④	Inner Leads	Nickel plated copper Wire
⑤	Resin body	Epoxy Resin
⑥	Frame: Pin	Nickel Plated Copper + Solder Dipped

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